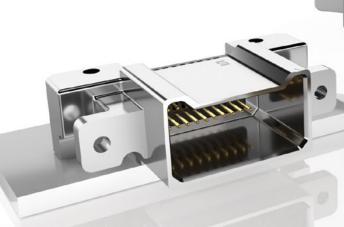


**ULTRA RUGGED I/O SYSTEMS** 

(1.00 mm) .0394" PITCH



## **FEATURES & BENEFITS**

- Small form factor
- Four points of contact for an extremely reliable connection
- Up to 40 positions per row
- Cable-to-cable & cable-to-board solutions
- EMI shielding in development to reduce noise generated and protect sensitive lines
- Through-hole or surface mount
- 28 & 30 AWG cable



Shown actual size at 20 total positions

Hyperboloid-type contact for extreme high mating cycles



Extreme density with up to 1,450 total I/Os in a 1RU panel (29 cables at 50 total I/Os each)

## KEY SPECIFICATIONS (P1PD(X), B1SD(X) & P1M)

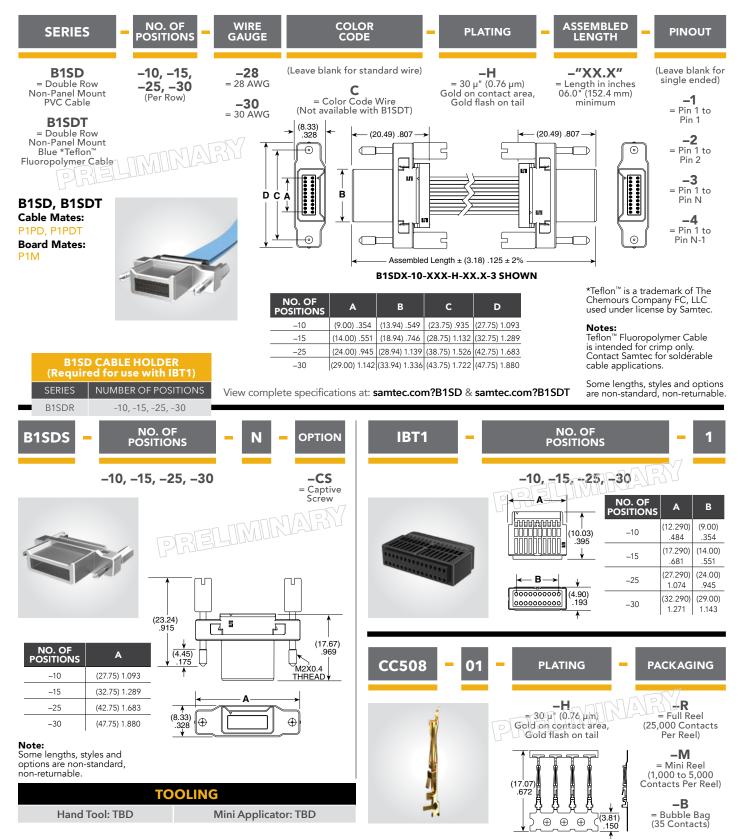
	PITCH	INSULATOR MATERIAL	CONTACT MATERIAL	SHIELD MATERIAL	PLATING	OPERATING TEMP RANGE	CURRENT RATING	VOLTAGE RATING
1	1.00 mm	Liquid Crystal Polymer	Beryllium Copper	Zinc Alloy	Au over 50 μ" (1.27 μm) Ni	-10 °C to +80 °C (PVC) -40 °C to +125 °C (*Teflon™ Fluoropolymer)	2.9 A per pin (2 pins powered)	253 VAC

<sup>\*</sup>Teflon™ is a trademark of The Chemours Company FC, LLC used under license by Samtec.





## (1.00 mm) .0394" PITCH • NON-PANEL MOUNT I/O CABLE/COMPONENTS



View complete specifications at: samtec.com?B1SDS, samtec.com?IBT1 & samtec.com?CC508